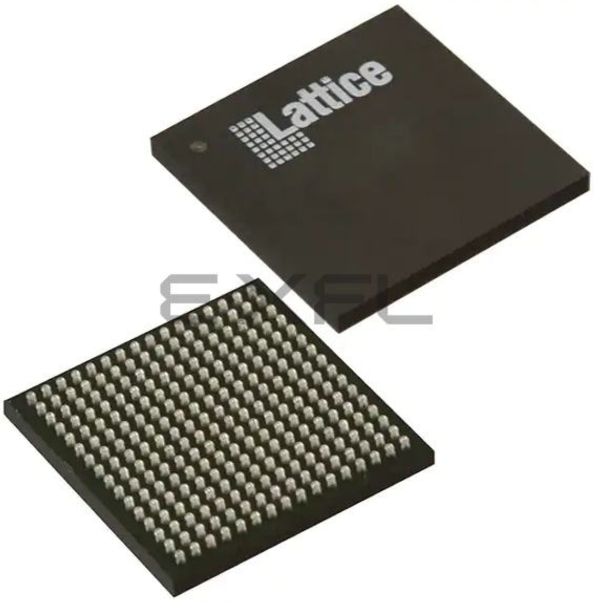
Lattice Semiconductor Corporation - LCMXO1200C-4BN256I Datasheet



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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	150
Number of Logic Elements/Cells	1200
Total RAM Bits	9421
Number of I/O	211
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-LFBGA, CSPBGA
Supplier Device Package	256-CABGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200c-4bn256i

MachXO Family Data Sheet
Introduction

June 2013 **Data Sheet DS1002**

Features

- **Non-volatile, Infinitely Reconfigurable**
  - Instant-on – powers up in microseconds
  - Single chip, no external configuration memory required
  - Excellent design security, no bit stream to intercept
  - Reconfigure SRAM based logic in milliseconds
  - SRAM and non-volatile memory programmable through JTAG port
  - Supports background programming of non-volatile memory
- **Sleep Mode**
  - Allows up to 100x static current reduction
- **TransFR™ Reconfiguration (TFR)**
  - In-field logic update while system operates
- **High I/O to Logic Density**
  - 256 to 2280 LUT4s
  - 73 to 271 I/Os with extensive package options
  - Density migration supported
  - Lead free/RoHS compliant packaging
- **Embedded and Distributed Memory**
  - Up to 27.6 Kbits sysMEM™ Embedded Block RAM
  - Up to 7.7 Kbits distributed RAM
  - Dedicated FIFO control logic
- **Flexible I/O Buffer**
  - Programmable sysIO™ buffer supports wide range of interfaces:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2
    - LVTTL
    - PCI
    - LVDS, Bus-LVDS, LVPECL, RSDS
- **sysCLOCK™ PLLs**
  - Up to two analog PLLs per device
  - Clock multiply, divide, and phase shifting
- **System Level Support**
  - IEEE Standard 1149.1 Boundary Scan
  - Onboard oscillator
  - Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply
  - IEEE 1532 compliant in-system programming

Introduction

The MachXO is optimized to meet the requirements of applications traditionally addressed by CPLDs and low capacity FPGAs: glue logic, bus bridging, bus interfacing, power-up control, and control logic. These devices bring together the best features of CPLD and FPGA devices on a single chip.

Table 1-1. MachXO Family Selection Guide

Device	LCMXO256	LCMXO640	LCMXO1200	LCMXO2280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V_{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
Packages				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

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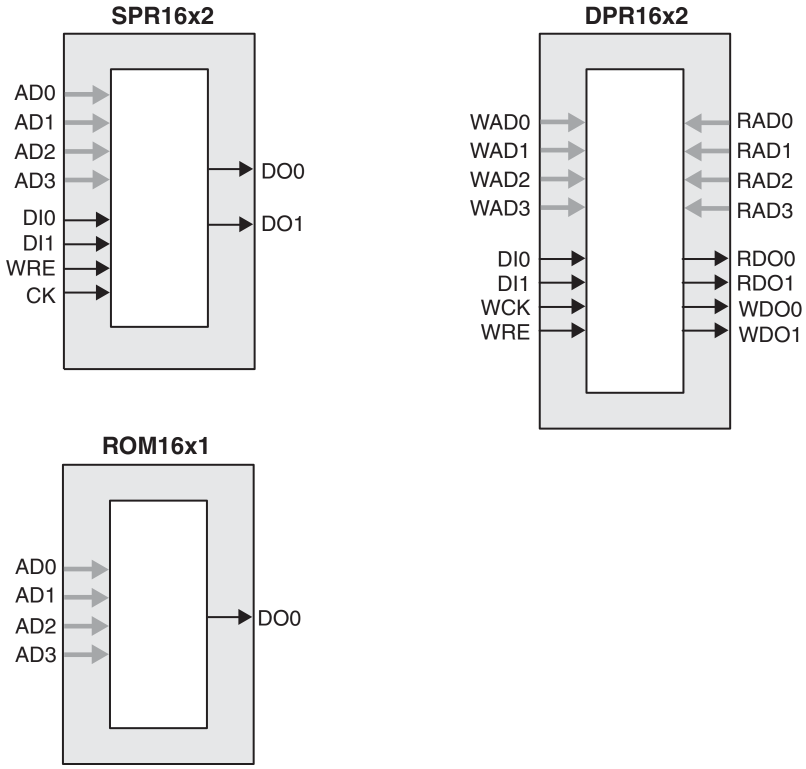
The devices use look-up tables (LUTs) and embedded block memories traditionally associated with FPGAs for flexible and efficient logic implementation. Through non-volatile technology, the devices provide the single-chip, high-security, instant-on capabilities traditionally associated with CPLDs. Finally, advanced process technology and careful design will provide the high pin-to-pin performance also associated with CPLDs.

The ispLEVER® design tools from Lattice allow complex designs to be efficiently implemented using the MachXO family of devices. Popular logic synthesis tools provide synthesis library support for MachXO. The ispLEVER tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the MachXO device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

of the devices also support differential input buffers. PCI clamps are available on the top Bank I/O buffers. The PCI clamp is enabled after V_{CC}, V_{CCAUX}, and V_{CCIO} are at valid operating levels and the device has been configured.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. **Left and Right sysIO Buffer Pairs**
   The sysIO buffer pairs in the left and right Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (supporting ratioed and absolute input levels). The devices also have a differential driver per output pair. The referenced input buffer can also be configured as a differential input buffer. In these Banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user’s responsibility to ensure that all V_{CCIO} Banks are active with valid input logic levels to properly control the output logic states of all the I/O Banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to VCCIO. The I/O pins will maintain the blank configuration until VCC, VCCAUX and VCCIO have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, the I/O buffers should be powered up along with the FPGA core fabric. Therefore, V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies

Supported Standards

The MachXO sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS and LVTTL. The buffer supports the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS and LVPECL output emulation is supported on all devices. The MachXO1200 and MachXO2280 support on-chip LVDS output buffers on approximately 50% of the I/Os on the left and right Banks. Differential receivers for LVDS, BLVDS and LVPECL are supported on all Banks of MachXO1200 and MachXO2280 devices. PCI support is provided in the top Banks of the MachXO1200 and MachXO2280 devices. Table 2-8 summarizes the I/O characteristics of the devices in the MachXO family.

Tables 2-9 and 2-10 show the I/O standards (together with their supply and reference voltages) supported by the MachXO devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Figure 2-20. MachXO640 Banks

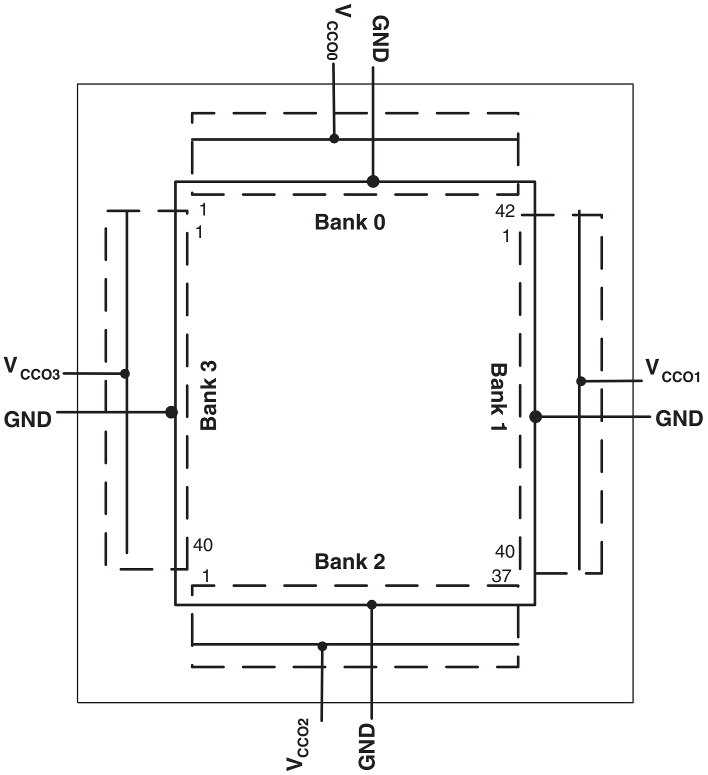
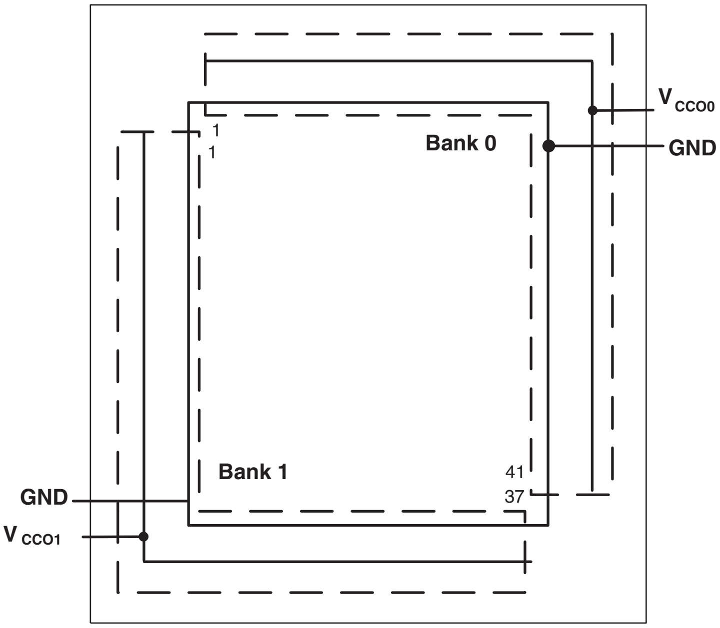


Figure 2-21. MachXO256 Banks



Hot Socketing

The MachXO devices have been carefully designed to ensure predictable behavior during power-up and power-down. Leakage into I/O pins is controlled to within specified limits. This allows for easy integration with the rest of

Device Configuration

All MachXO devices contain a test access port that can be used for device configuration and programming.

The non-volatile memory in the MachXO can be configured in two different modes:

- In IEEE 1532 mode via the IEEE 1149.1 port. In this mode, the device is off-line and I/Os are controlled by BSCAN registers.
- In background mode via the IEEE 1149.1 port. This allows the device to remain operational in user mode while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- After a refresh command is issued via the IEEE 1149.1 port.
- In IEEE 1532 mode via the IEEE 1149.1 port.

Figure 2-22 provides a pictorial representation of the different programming modes available in the MachXO devices. On power-up, the SRAM is ready to be configured with IEEE 1149.1 serial TAP port using IEEE 1532 protocols.

Leave Alone I/O

When using IEEE 1532 mode for non-volatile memory programming, SRAM configuration, or issuing a refresh command, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reconfiguration or reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

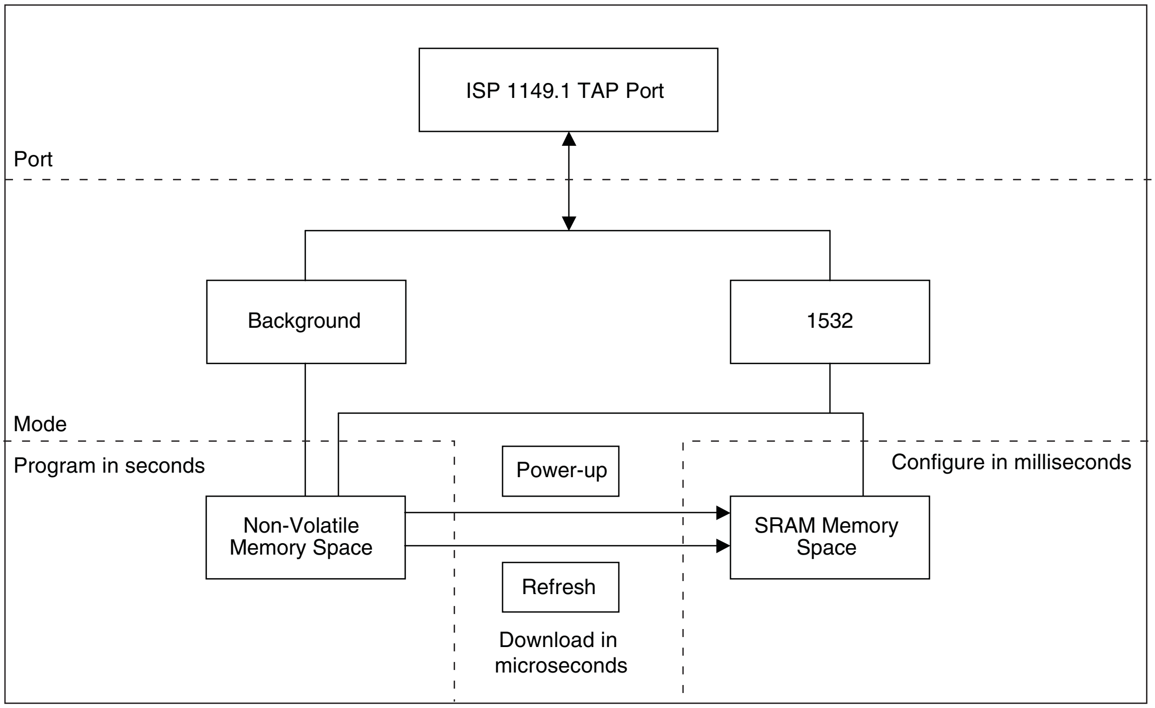
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See TN1087, Minimizing System Interruption During Configuration Using TransFR Technology for details.

Security

The MachXO devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear the security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Figure 2-22. MachXO Configuration and Programming



Density Shifting

The MachXO family has been designed to enable density migration in the same package. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Supply Current (Sleep Mode)[1, 2]

Symbol	Parameter	Device	Typ.[3]	Max.	Units
I_{CC}	Core Power Supply	LCMXO256C	12	25	µA
		LCMXO640C	12	25	µA
		LCMXO1200C	12	25	µA
		LCMXO2280C	12	25	µA
I_{CCAUX}	Auxiliary Power Supply	LCMXO256C	1	15	µA
		LCMXO640C	1	25	µA
		LCMXO1200C	1	45	µA
		LCMXO2280C	1	85	µA
I_{CCIO}	Bank Power Supply[4]	All LCMXO 'C' Devices	2	30	µA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.
2. Frequency = 0MHz.
3. T_A = 25°C, power supplies at nominal voltage.
4. Per Bank.

Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO256C	7	mA
		LCMXO640C	9	mA
		LCMXO1200C	14	mA
		LCMXO2280C	20	mA
		LCMXO256E	4	mA
		LCMXO640E	6	mA
		LCMXO1200E	10	mA
		LCMXO2280E	12	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LCMXO256E/C	5	mA
		LCMXO640E/C	7	mA
		LCMXO1200E/C	12	mA
		LCMXO2280E/C	13	mA
I_{CCIO}	Bank Power Supply[6]	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND.
3. Frequency = 0MHz.
4. User pattern = blank.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank. V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

Initialization Supply Current[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO256C	13	mA
		LCMXO640C	17	mA
		LCMXO1200C	21	mA
		LCMXO2280C	23	mA
		LCMXO256E	10	mA
		LCMXO640E	14	mA
		LCMXO1200E	18	mA
		LCMXO2280E	20	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LCMXO256E/C	10	mA
		LCMXO640E/C	13	mA
		LCMXO1200E/C	24	mA
		LCMXO2280E/C	25	mA
I_{CCIO}	Bank Power Supply[6]	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all I/O pins are held at V_{CCIO} or GND.
3. Frequency = 0MHz.
4. Typical user pattern.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank, V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

Programming and Erase Flash Supply Current[1, 2, 3, 4]

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO256C	9	mA
		LCMXO640C	11	mA
		LCMXO1200C	16	mA
		LCMXO2280C	22	mA
		LCMXO256E	6	mA
		LCMXO640E	8	mA
		LCMXO1200E	12	mA
		LCMXO2280E	14	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LCMXO256C/E	8	mA
		LCMXO640C/E	10	mA
		LCMXO1200/E	15	mA
		LCMXO2280C/E	16	mA
I_{CCIO}	Bank Power Supply[6]	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all I/O pins are held at V_{CCIO} or GND.
3. Typical user pattern.
4. JTAG programming is at 25MHz.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank. V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

Table 3-1. LVDS DC Conditions

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ω
R_S	Driver series resistor	294	Ω
R_P	Driver parallel resistor	121	Ω
R_T	Receiver termination	100	Ω
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	Ω
I_{DC}	DC output current	3.66	mA

BLVDS

The MachXO family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. The input standard is supported by the LVDS differential input buffer on certain devices. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example

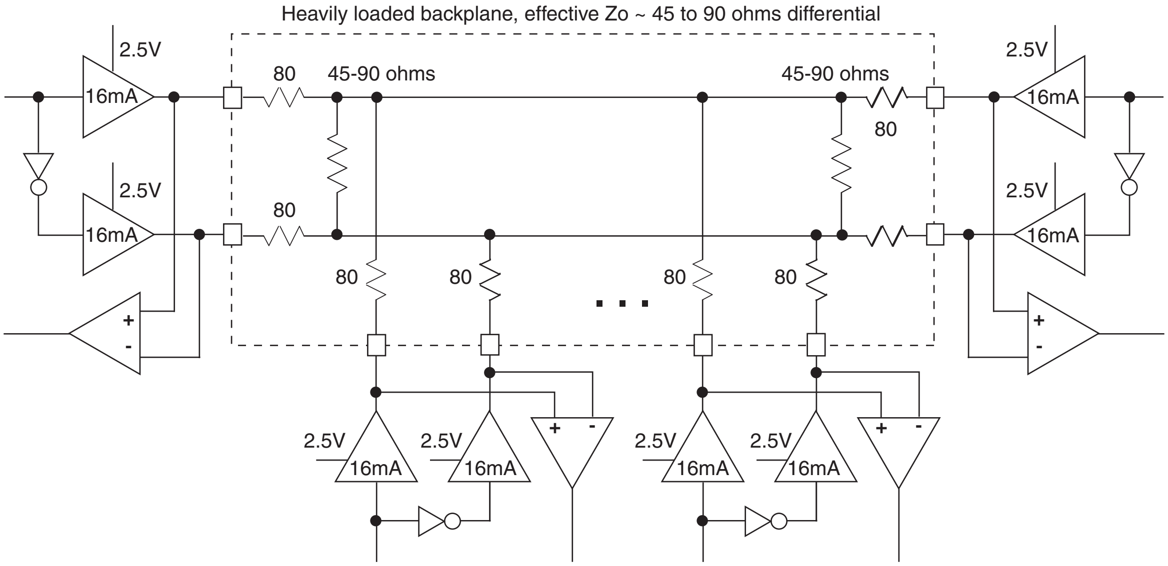


Table 3-2. BLVDS DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal		Units
		Zo = 45	Zo = 90	
Z_{OUT}	Output impedance	100	100	Ohms
R_{TLEFT}	Left end termination	45	90	Ohms
R_{TRIGHT}	Right end termination	45	90	Ohms
V_{OH}	Output high voltage	1.375	1.48	V
V_{OL}	Output low voltage	1.125	1.02	V
V_{OD}	Output differential voltage	0.25	0.46	V
V_{CM}	Output common mode voltage	1.25	1.25	V
I_{DC}	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

LVPECL

The MachXO family supports the differential LVPECL standard through emulation. This output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The LVPECL input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

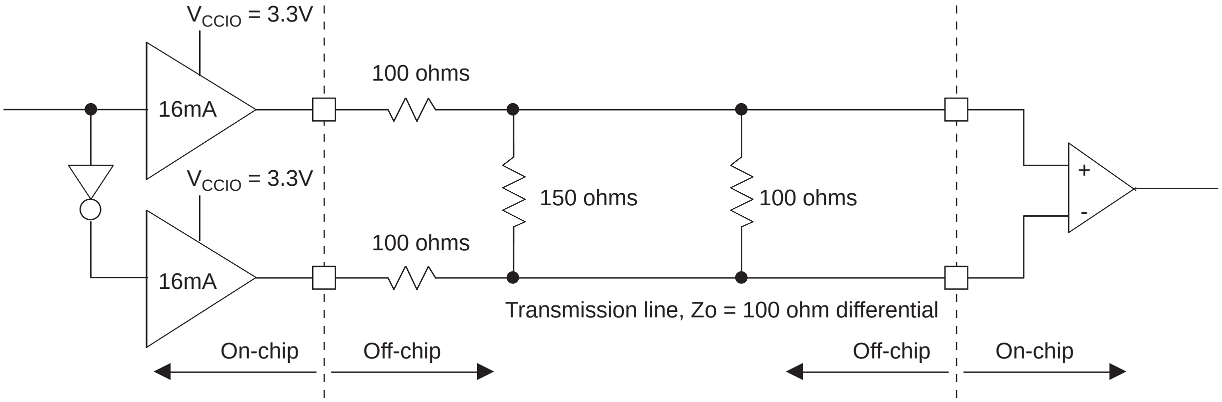


Table 3-3. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal	Units
Z_{OUT}	Output impedance	100	Ohms
R_P	Driver parallel resistor	150	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	85.7	Ohms
I_{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

MachXO Internal Timing Parameters[1]

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t_{LUT4_PFU}	LUT4 delay (A to D inputs to F output)	—	0.28	—	0.34	—	0.39	ns
t_{LUT6_PFU}	LUT6 delay (A to D inputs to OFX output)	—	0.44	—	0.53	—	0.62	ns
t_{LSR_PFU}	Set/Reset to output of PFU	—	0.90	—	1.08	—	1.26	ns
t_{SUM_PFU}	Clock to Mux (M0,M1) input setup time	0.10	—	0.13	—	0.15	—	ns
t_{HM_PFU}	Clock to Mux (M0,M1) input hold time	-0.05	—	-0.06	—	-0.07	—	ns
t_{SUD_PFU}	Clock to D input setup time	0.13	—	0.16	—	0.18	—	ns
t_{HD_PFU}	Clock to D input hold time	-0.03	—	-0.03	—	-0.04	—	ns
t_{CK2Q_PFU}	Clock to Q delay, D-type register configuration	—	0.40	—	0.48	—	0.56	ns
t_{LE2Q_PFU}	Clock to Q delay latch configuration	—	0.53	—	0.64	—	0.74	ns
t_{LD2Q_PFU}	D to Q throughput delay when latch is enabled	—	0.55	—	0.66	—	0.77	ns
PFU Dual Port Memory Mode Timing								
t_{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.56	ns
t_{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.22	—	-0.25	—	ns
t_{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.39	—	ns
t_{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.56	—	-0.65	—	ns
t_{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	0.99	—	ns
t_{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.26	—	-0.30	—	ns
t_{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.47	—	ns
PIO Input/Output Buffer Timing								
t_{IN_PIO}	Input Buffer Delay	—	0.75	—	0.90	—	1.06	ns
t_{OUT_PIO}	Output Buffer Delay	—	1.29	—	1.54	—	1.80	ns
EBR Timing (1200 and 2280 Devices Only)								
t_{CO_EBR}	Clock to output from Address or Data with no output register	—	2.24	—	2.69	—	3.14	ns
t_{COO_EBR}	Clock to output from EBR output Register	—	0.54	—	0.64	—	0.75	ns
t_{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t_{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t_{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t_{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t_{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.20	—	-0.23	—	ns
t_{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.36	—	ns
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.27	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.16	—	-0.18	—	ns
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.23	—	1.44	ns
PLL Parameters (1200 and 2280 Devices Only)								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

Rev. A 0.19

LCMXO1200 and LCMXO2280 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
42	PB9A	4		T	PB12A	4		T
43	PB9B	4		C	PB12B	4		C
44	VCCIO4	4			VCCIO4	4		
45	PB10A	4		T	PB13A	4		T
46	PB10B	4		C	PB13B	4		C
47***	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
48	PB11A	4		T	PB16A	4		T
49	PB11B	4		C	PB16B	4		C
50**	GNDIO3 GNDIO4	-			GNDIO3 GNDIO4	-		
51	PR16B	3			PR19B	3		
52	PR15B	3		C*	PR18B	3		C*
53	PR15A	3		T*	PR18A	3		T*
54	PR14B	3		C*	PR17B	3		C*
55	PR14A	3		T*	PR17A	3		T*
56	VCCIO3	3			VCCIO3	3		
57	PR12B	3		C*	PR15B	3		C*
58	PR12A	3		T*	PR15A	3		T*
59	GND	-			GND	-		
60	PR10B	3		C*	PR13B	3		C*
61	PR10A	3		T*	PR13A	3		T*
62	PR9B	3		C*	PR11B	3		C*
63	PR9A	3		T*	PR11A	3		T*
64	PR8B	2		C*	PR10B	2		C*
65	PR8A	2		T*	PR10A	2		T*
66	VCC	-			VCC	-		
67	PR6C	2			PR8C	2		
68	PR6B	2		C*	PR8B	2		C*
69	PR6A	2		T*	PR8A	2		T*
70	VCCIO2	2			VCCIO2	2		
71	PR4D	2			PR5D	2		
72	PR4B	2		C*	PR5B	2		C*
73	PR4A	2		T*	PR5A	2		T*
74	PR2B	2		C	PR3B	2		C*
75	PR2A	2		T	PR3A	2		T*
76**	GNDIO1 GNDIO2	-			GNDIO1 GNDIO2	-		
77	PT11C	1			PT15C	1		
78	PT11B	1		C	PT14B	1		C
79	PT11A	1		T	PT14A	1		T
80	VCCIO1	1			VCCIO1	1		
81	PT9E	1			PT12D	1		C

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
101	PR3D	1		C	PR4B	2		C*	PR5B	2		C*
102	PR3C	1		T	PR4A	2		T*	PR5A	2		T*
103	PR3B	1		C	PR3D	2		C	PR4D	2		C
104	PR2D	1		C	PR3C	2		T	PR4C	2		T
105	PR3A	1		T	PR3B	2		C*	PR4B	2		C*
106	PR2B	1		C	PR3A	2		T*	PR4A	2		T*
107	PR2C	1		T	PR2B	2		C	PR3B	2		C*
108	PR2A	1		T	PR2A	2		T	PR3A	2		T*
109	PT9F	0		C	PT11D	1		C	PT16D	1		C
110	PT9D	0		C	PT11C	1		T	PT16C	1		T
111	PT9E	0		T	PT11B	1		C	PT16B	1		C
112	PT9B	0		C	PT11A	1		T	PT16A	1		T
113	PT9C	0		T	PT10F	1		C	PT15D	1		C
114	PT9A	0		T	PT10E	1		T	PT15C	1		T
115	PT8C	0			PT10D	1		C	PT14B	1		C
116	PT8B	0		C	PT10C	1		T	PT14A	1		T
117	VCCIO0	0			VCCIO1	1			VCCIO1	1		
118	GNDIO0	0			GNDIO1	1			GNDIO1	1		
119	PT8A	0		T	PT9F	1		C	PT12F	1		C
120	PT7E	0			PT9E	1		T	PT12E	1		T
121	PT7C	0			PT9B	1		C	PT12D	1		C
122	PT7A	0			PT9A	1		T	PT12C	1		T
123	GND	-			GND	-			GND	-		
124	PT6B	0	PCLK0_1***	C	PT7D	1	PCLK1_1***		PT10B	1	PCLK1_1***	
125	PT6A	0		T	PT7B	1		C	PT9D	1		C
126	PT5C	0			PT7A	1		T	PT9C	1		T
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***		PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-			VCCAUX	-		
129	VCC	-			VCC	-			VCC	-		
130	PT4D	0			PT5D	0		C	PT7B	0		C
131	PT4B	0		C	PT5C	0		T	PT7A	0		T
132	PT4A	0		T	PT5B	0		C	PT6D	0		
133	PT3F	0			PT5A	0		T	PT6E	0		T
134	PT3D	0			PT4B	0			PT6F	0		C
135	VCCIO0	0			VCCIO0	0			VCCIO0	0		
136	GNDIO0	0			GNDIO0	0			GNDIO0	0		
137	PT3B	0		C	PT3D	0		C	PT4B	0		T
138	PT2F	0		C	PT3C	0		T	PT4A	0		C
139	PT3A	0		T	PT3B	0		C	PT3B	0		C
140	PT2D	0		C	PT3A	0		T	PT3A	0		T
141	PT2E	0		T	PT2D	0		C	PT2D	0		C
142	PT2B	0		C	PT2C	0		T	PT2C	0		T
143	PT2C	0		T	PT2B	0		C	PT2B	0		C
144	PT2A	0		T	PT2A	0		T	PT2A	0		T

*Supports true LVDS outputs.
**NC for “E” devices.
***Primary clock inputs arer single-ended.

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
E13	PT16D	1		C
C15	PT16C	1		T
F13	PT16B	1		C
D14	PT16A	1		T
A18	PT15D	1		C
B17	PT15C	1		T
A16	PT15B	1		C
A17	PT15A	1		T
VCC	VCC	-		
D13	PT14D	1		C
F12	PT14C	1		T
C14	PT14B	1		C
E12	PT14A	1		T
C13	PT13D	1		C
B16	PT13C	1		T
B15	PT13B	1		C
A15	PT13A	1		T
VCCIO1	VCCIO1	1		
GND	GNDIO1	1		
B14	PT12F	1		C
A14	PT12E	1		T
D12	PT12D	1		C
F11	PT12C	1		T
B13	PT12B	1		C
A13	PT12A	1		T
C12	PT11D	1		C
GND	GND	-		
B12	PT11C	1		T
E11	PT11B	1		C
D11	PT11A	1		T
C11	PT10F	1		C
A12	PT10E	1		T
VCCIO1	VCCIO1	1		
GND	GNDIO1	1		
F10	PT10D	1		C
D10	PT10C	1		T
B11	PT10B	1	PCLK1_1***	C
A11	PT10A	1		T
E10	PT9D	1		C
C10	PT9C	1		T
D9	PT9B	1	PCLK1_0***	C
E9	PT9A	1		T
B10	PT8F	0		C

Conventional Packaging

Commercial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3T100C	256	1.8V/2.5V/3.3V	78	-3	TQFP	100	COM
LCMXO256C-4T100C	256	1.8V/2.5V/3.3V	78	-4	TQFP	100	COM
LCMXO256C-5T100C	256	1.8V/2.5V/3.3V	78	-5	TQFP	100	COM
LCMXO256C-3M100C	256	1.8V/2.5V/3.3V	78	-3	csBGA	100	COM
LCMXO256C-4M100C	256	1.8V/2.5V/3.3V	78	-4	csBGA	100	COM
LCMXO256C-5M100C	256	1.8V/2.5V/3.3V	78	-5	csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640C-3T100C	640	1.8V/2.5V/3.3V	74	-3	TQFP	100	COM
LCMXO640C-4T100C	640	1.8V/2.5V/3.3V	74	-4	TQFP	100	COM
LCMXO640C-5T100C	640	1.8V/2.5V/3.3V	74	-5	TQFP	100	COM
LCMXO640C-3M100C	640	1.8V/2.5V/3.3V	74	-3	csBGA	100	COM
LCMXO640C-4M100C	640	1.8V/2.5V/3.3V	74	-4	csBGA	100	COM
LCMXO640C-5M100C	640	1.8V/2.5V/3.3V	74	-5	csBGA	100	COM
LCMXO640C-3T144C	640	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMXO640C-4T144C	640	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMXO640C-5T144C	640	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMXO640C-3M132C	640	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMXO640C-4M132C	640	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMXO640C-5M132C	640	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMXO640C-3B256C	640	1.8V/2.5V/3.3V	159	-3	caBGA	256	COM
LCMXO640C-4B256C	640	1.8V/2.5V/3.3V	159	-4	caBGA	256	COM
LCMXO640C-5B256C	640	1.8V/2.5V/3.3V	159	-5	caBGA	256	COM
LCMXO640C-3FT256C	640	1.8V/2.5V/3.3V	159	-3	ftBGA	256	COM
LCMXO640C-4FT256C	640	1.8V/2.5V/3.3V	159	-4	ftBGA	256	COM
LCMXO640C-5FT256C	640	1.8V/2.5V/3.3V	159	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3T100C	1200	1.8V/2.5V/3.3V	73	-3	TQFP	100	COM
LCMXO1200C-4T100C	1200	1.8V/2.5V/3.3V	73	-4	TQFP	100	COM
LCMXO1200C-5T100C	1200	1.8V/2.5V/3.3V	73	-5	TQFP	100	COM
LCMXO1200C-3T144C	1200	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMXO1200C-4T144C	1200	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMXO1200C-5T144C	1200	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMXO1200C-3M132C	1200	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMXO1200C-4M132C	1200	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMXO1200C-5M132C	1200	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMXO1200C-3B256C	1200	1.8V/2.5V/3.3V	211	-3	caBGA	256	COM
LCMXO1200C-4B256C	1200	1.8V/2.5V/3.3V	211	-4	caBGA	256	COM
LCMXO1200C-5B256C	1200	1.8V/2.5V/3.3V	211	-5	caBGA	256	COM
LCMXO1200C-3FT256C	1200	1.8V/2.5V/3.3V	211	-3	ftBGA	256	COM
LCMXO1200C-4FT256C	1200	1.8V/2.5V/3.3V	211	-4	ftBGA	256	COM
LCMXO1200C-5FT256C	1200	1.8V/2.5V/3.3V	211	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3T100C	1200	1.2V	73	-3	TQFP	100	COM
LCMXO1200E-4T100C	1200	1.2V	73	-4	TQFP	100	COM
LCMXO1200E-5T100C	1200	1.2V	73	-5	TQFP	100	COM
LCMXO1200E-3T144C	1200	1.2V	113	-3	TQFP	144	COM
LCMXO1200E-4T144C	1200	1.2V	113	-4	TQFP	144	COM
LCMXO1200E-5T144C	1200	1.2V	113	-5	TQFP	144	COM
LCMXO1200E-3M132C	1200	1.2V	101	-3	csBGA	132	COM
LCMXO1200E-4M132C	1200	1.2V	101	-4	csBGA	132	COM
LCMXO1200E-5M132C	1200	1.2V	101	-5	csBGA	132	COM
LCMXO1200E-3B256C	1200	1.2V	211	-3	caBGA	256	COM
LCMXO1200E-4B256C	1200	1.2V	211	-4	caBGA	256	COM
LCMXO1200E-5B256C	1200	1.2V	211	-5	caBGA	256	COM
LCMXO1200E-3FT256C	1200	1.2V	211	-3	ftBGA	256	COM
LCMXO1200E-4FT256C	1200	1.2V	211	-4	ftBGA	256	COM
LCMXO1200E-5FT256C	1200	1.2V	211	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3T100C	2280	1.2V	73	-3	TQFP	100	COM
LCMXO2280E-4T100C	2280	1.2V	73	-4	TQFP	100	COM
LCMXO2280E-5T100C	2280	1.2V	73	-5	TQFP	100	COM
LCMXO2280E-3T144C	2280	1.2V	113	-3	TQFP	144	COM
LCMXO2280E-4T144C	2280	1.2V	113	-4	TQFP	144	COM
LCMXO2280E-5T144C	2280	1.2V	113	-5	TQFP	144	COM
LCMXO2280E-3M132C	2280	1.2V	101	-3	csBGA	132	COM
LCMXO2280E-4M132C	2280	1.2V	101	-4	csBGA	132	COM
LCMXO2280E-5M132C	2280	1.2V	101	-5	csBGA	132	COM
LCMXO2280E-3B256C	2280	1.2V	211	-3	caBGA	256	COM
LCMXO2280E-4B256C	2280	1.2V	211	-4	caBGA	256	COM
LCMXO2280E-5B256C	2280	1.2V	211	-5	caBGA	256	COM
LCMXO2280E-3FT256C	2280	1.2V	211	-3	ftBGA	256	COM
LCMXO2280E-4FT256C	2280	1.2V	211	-4	ftBGA	256	COM
LCMXO2280E-5FT256C	2280	1.2V	211	-5	ftBGA	256	COM
LCMXO2280E-3FT324C	2280	1.2V	271	-3	ftBGA	324	COM
LCMXO2280E-4FT324C	2280	1.2V	271	-4	ftBGA	324	COM
LCMXO2280E-5FT324C	2280	1.2V	271	-5	ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3T100I	256	1.2V	78	-3	TQFP	100	IND
LCMXO256E-4T100I	256	1.2V	78	-4	TQFP	100	IND
LCMXO256E-3M100I	256	1.2V	78	-3	csBGA	100	IND
LCMXO256E-4M100I	256	1.2V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3T100I	640	1.2V	74	-3	TQFP	100	IND
LCMXO640E-4T100I	640	1.2V	74	-4	TQFP	100	IND
LCMXO640E-3M100I	640	1.2V	74	-3	csBGA	100	IND
LCMXO640E-4M100I	640	1.2V	74	-4	csBGA	100	IND
LCMXO640E-3T144I	640	1.2V	113	-3	TQFP	144	IND
LCMXO640E-4T144I	640	1.2V	113	-4	TQFP	144	IND
LCMXO640E-3M132I	640	1.2V	101	-3	csBGA	132	IND
LCMXO640E-4M132I	640	1.2V	101	-4	csBGA	132	IND
LCMXO640E-3B256I	640	1.2V	159	-3	caBGA	256	IND
LCMXO640E-4B256I	640	1.2V	159	-4	caBGA	256	IND
LCMXO640E-3FT256I	640	1.2V	159	-3	ftBGA	256	IND
LCMXO640E-4FT256I	640	1.2V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3T100I	1200	1.2V	73	-3	TQFP	100	IND
LCMXO1200E-4T100I	1200	1.2V	73	-4	TQFP	100	IND
LCMXO1200E-3T144I	1200	1.2V	113	-3	TQFP	144	IND
LCMXO1200E-4T144I	1200	1.2V	113	-4	TQFP	144	IND
LCMXO1200E-3M132I	1200	1.2V	101	-3	csBGA	132	IND
LCMXO1200E-4M132I	1200	1.2V	101	-4	csBGA	132	IND
LCMXO1200E-3B256I	1200	1.2V	211	-3	caBGA	256	IND
LCMXO1200E-4B256I	1200	1.2V	211	-4	caBGA	256	IND
LCMXO1200E-3FT256I	1200	1.2V	211	-3	ftBGA	256	IND
LCMXO1200E-4FT256I	1200	1.2V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3T100I	2280	1.2V	73	-3	TQFP	100	IND
LCMXO2280E-4T100I	2280	1.2V	73	-4	TQFP	100	IND
LCMXO2280E-3T144I	2280	1.2V	113	-3	TQFP	144	IND
LCMXO2280E-4T144I	2280	1.2V	113	-4	TQFP	144	IND
LCMXO2280E-3M132I	2280	1.2V	101	-3	csBGA	132	IND
LCMXO2280E-4M132I	2280	1.2V	101	-4	csBGA	132	IND
LCMXO2280E-3B256I	2280	1.2V	211	-3	caBGA	256	IND
LCMXO2280E-4B256I	2280	1.2V	211	-4	caBGA	256	IND
LCMXO2280E-3FT256I	2280	1.2V	211	-3	ftBGA	256	IND
LCMXO2280E-4FT256I	2280	1.2V	211	-4	ftBGA	256	IND
LCMXO2280E-3FT324I	2280	1.2V	271	-3	ftBGA	324	IND
LCMXO2280E-4FT324I	2280	1.2V	271	-4	ftBGA	324	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3TN100C	1200	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMXO1200E-4TN100C	1200	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMXO1200E-5TN100C	1200	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMXO1200E-3TN144C	1200	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO1200E-4TN144C	1200	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO1200E-5TN144C	1200	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO1200E-3MN132C	1200	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO1200E-4MN132C	1200	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO1200E-5MN132C	1200	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO1200E-3BN256C	1200	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMXO1200E-4BN256C	1200	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMXO1200E-5BN256C	1200	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMXO1200E-3FTN256C	1200	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMXO1200E-4FTN256C	1200	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMXO1200E-5FTN256C	1200	1.2V	211	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3TN100C	2280	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMXO2280E-4TN100C	2280	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMXO2280E-5TN100C	2280	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMXO2280E-3TN144C	2280	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO2280E-4TN144C	2280	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO2280E-5TN144C	2280	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO2280E-3MN132C	2280	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO2280E-4MN132C	2280	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO2280E-5MN132C	2280	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO2280E-3BN256C	2280	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMXO2280E-4BN256C	2280	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMXO2280E-5BN256C	2280	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMXO2280E-3FTN256C	2280	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMXO2280E-4FTN256C	2280	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMXO2280E-5FTN256C	2280	1.2V	211	-5	Lead-Free ftBGA	256	COM
LCMXO2280E-3FTN324C	2280	1.2V	271	-3	Lead-Free ftBGA	324	COM
LCMXO2280E-4FTN324C	2280	1.2V	271	-4	Lead-Free ftBGA	324	COM
LCMXO2280E-5FTN324C	2280	1.2V	271	-5	Lead-Free ftBGA	324	COM

MachXO Family Data Sheet
Revision History

June 2013 **Data Sheet DS1002**

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
			Security section updated.
		DC and Switching Characteristics	Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timingupdated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
			JTAG Port Timing Specification updated (rev. A 0.16).
		Pinout Information	SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connection section has been updated to include all devices/packages.
		Ordering Information	Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/ LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added “Power Supply and NC Connections” summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.

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